## **EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	10	((insulating or insulation or dielectric) and (Copper or Cu) and (trench or groove) and metal\$3 and (CMP or "chemical mechanical polishing") and plasma and (ammonia or "NH.sub.3") and barrier and interconnect\$4).clm.	US-PGPUB	OR	ON	2006/02/28 15:07
L3	3	((insulating or insulation or dielectric) and (Copper or Cu) and (trench or groove) and metal\$3 and (CMP or "chemical mechanical polishing") and plasma and (ammonia or "NH.sub.3") and clean\$4 and interconnect\$4).clm.	US-PGPUB	OR	ON	2006/02/28 15:08
L4	119	noguchi-junji.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 15:10
L5	9	asaka-shoji.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 15:12
L6	39	konishi-nobuhiro.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 15:12
L7	465	maruyama-hiroyuki.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 15:13